

# The Big Deal

- Patented design eliminates in band spurs
- Pass band cut-off up to 21 GHz
- Stop band up to 35 GHz
- Excellent repeatability through IPD\* process



Available in Low Pass, High Pass and Band Pass designs

# **Product Overview**

Mini-Circuits' *X-Series* reflectionless filters employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level which interact with neighboring components and often result in intermodulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

Key Features	Advantages
Easy integration with sensitive reflective components, e.g. mixers, multipliers	Reflectionless filters absorb unwanted signals, preventing reflections back to the source. This reduces generation of additional unwanted signals without the need for extra components like attenuators, improving system dynamic range and saving board space.
Enables stable integration of wideband amplifiers	Because reflectionless filters maintain good impedance in the stop band; they can be integrated with high gain, wideband amplifiers without the risk of creating instabilities in these out of band regions.
Cascadable	Reflectionless filters can be cascaded in multiple sections to provide sharper and higher attenuation, while also preventing any standing waves that could affect pass band signals.
Excellent power handling in a tiny surface mount device	High power handling extends the usability of these filters to the transmit path for inter-stage filtering.
Small size, 3x3mm QFN	Allows replacement of filter/attenuator pairs with a single reflectionless filter, sav- ing board space.
Excellent repeatability of RF performance	Through semiconductor IPD process, X-series filters are inherently repeatable for large volume production.
Excellent stability over temperature	With $\pm 0.3$ dB variation over temperature ideal for use in wide temperature range applications without the need for additional temperature compensation.
Operating temperature up to 105°C	Suitable for operation close to high power components.

\*IPD - Integrated Passive Device, is a GaAs semiconductor process

# Reflectionless

# 50Ω DC to 13100 MHz

#### Features

- Match to  $50\Omega$  in the stop band, eliminates undesired reflections
- Cascadable
- Excellent Power handling
- Temperature stable, up to 105°C
- Small size, 3 x 3 mm
- Protected by US Patent No. 8,392,495

#### Applications

- Harmonics Rejection
- Satellite
- Radar
- Military & Space

# **General Description**





Generic photo used for illustration purposes only CASE STYLE: DQ1225

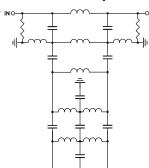
+RoHS Compliant The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

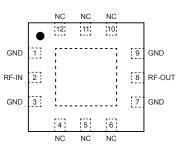
Available Tape and Reel at no extra cost				
Reel Size	Devices/Reel			
7"	20, 50, 100, 200, 500, 1000, 2000			

Mini-Circuits' XLF-133+ reflectionless filter employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level. These reflections interact with neighboring components and often result in inter-modulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

OUT

#### simplified schematic and pad description





Function	Pad Number	Description
RF-IN	2	RF Input Pad
RF-OUT	8	RF Output Pad
GND	1,3,7,9, Paddle	Connected to ground
NC (GND Externally)	4,5,6,10,11,12	No internal connection

### Electrical Specifications<sup>1</sup> at 25°C

Parameter		F#	Frequency (MHz)	Min.	Тур.	Max.	Unit
	Insertion Loss	DC - F1	DC-13100	—	2.0	2.4	dB
Pass Band	Frequency Cut-off	F2	15800	—	3.0	—	dB
	VSWR	DC - F1	DC-13100	—	1.3	—	:1
		F3 - F4	19500 - 20000	13	16	_	dB
	Rejection	F4 - F5	20000 - 30000	18	21	_	dB
Stop Band							:1
	VSWR	F3 - F4	19500 - 20000	—	1.5	—	.1
		F4 - F5	20000 - 30000	—	2.7	—	:1

<sup>1</sup> Measured on Mini-Circuits Characterization Test Board TB-844-133+

# Absolute Maximum Ratings<sup>4</sup>

Parameter	Ratings
Operating Temperature	-55°C to +105°C
Storage Temperature	-65°C to +150°C
RF Power Input, Passband (DC-F1) <sup>2</sup>	2W at 25°C
RF Power Input, Stopband (F2-F5) <sup>3</sup>	50mW at 25°C

 $^{\scriptscriptstyle 2}$  Passband rating derates linearly to 1W at 105°C ambient

Stopband rating derates linearly to 25mW at 105°C ambient
Permanent damage may occur if any of these limits are exceeded.

#### **ESD** rating

Human body model (HBM): Class 1A (250 to <500V) in accordance with ANSI/ESD 5.1-2001

#### MSL rating

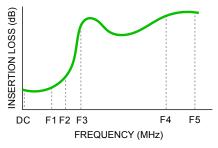
Moisture Sensitivity: MSL1 in accordance with IPC/JEDEC J-STD-020D

#### Typical Performance Data at 25°C Frequency (MHz) Insertion Loss VSWR (dB) (:1) 10 0.34 1.02 100 200 400 0.33 1.02 0.36 1.04 0.42 1.08 800 1600 3200 0.56 1.14 0.77 1.22 1.19 1.07 5000 1.22 1.16 7000 9000 1.09 1.24 1.18 1.25 11000 1.81 1.73 13100 1.94 1.60 15800 17500 3.15 6.49 1.55 1.69 19500 18.98 1.58 20000 24.37 1.72 22500 30.09 4.80 25000 21.52 2.37 27500 26.48 1.91 30000 24.30 4.05 XLF-133+ VSWR XLF-133+ INSERTION LOSS 40 5.0 INSERTION LOSS (dB) 30 4.0 VSWR 3.0 20 10 2.0 1.0 0 0 6000 12000 18000 24000 30000 0 6000 12000 18000 24000 30000 FREQUENCY (MHz) FREQUENCY (MHz)

# **Mini-Circuits**

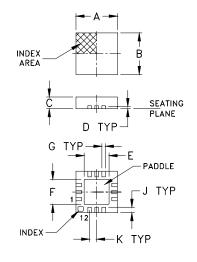
www.minicircuits.com P.O. Box 350166, Brooklyn, NY 11235-0003 (718) 934-4500 sales@minicircuits.com

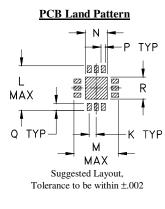
#### Specification Definition



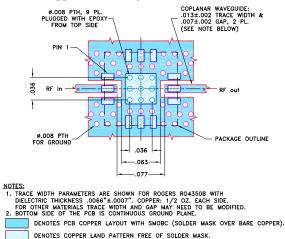
# XLF-133+

# **Outline Drawing**





Demo Board MCL P/N: TB-844-133+ (without connectors) TB-844-133C+ (with connectors) B20-118-F1+ Connector sold separately Suggested PCB Layout: PL-451+



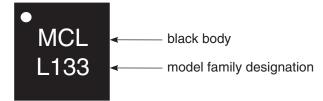
# Outline Dimensions ( inch )

J	н	G	F	Е	D	С	В	А
.016		.009	.057	.057	.008	.035	.118	.118
0.41		0.23	1.45	1.45	0.20	0.89	3.00	3.00
		Б	~	п				LZ.
wt		г	Q	Р	IN	IVI	L	n
wt grams				-		.127	_	
		.049	.020	.010	.049		.127	.020

# **Tape & Reel Packaging**

DEVICE ORIENTATION IN T&R

# **Product Marking**



DIRECTION	OF	FEED
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Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel see note	
8	4	7	Small quantity standard	20 50 100 200 500
		7	Standard	1000, 2000

